

In the Claims

This listing of claims will replace all prior versions, and listings, of claims.

Listing of Claims

1. (Currently amended) A bonding pad structure, comprising:

a bonding pad substantially surrounded and insulated by a dielectric layer, wherein the bonding pad comprises at least one first conductive layer having a wiring layer with a stripe layout and a first edge portion, a second conductive layer having a wire bonding portion and a second edge portion and a plurality of plugs electrically connecting the wiring layer and the wire bonding portion; and

[[a]] an array of conductive structures surrounding the

wire bonding portion, connecting the first edge portion and the second edge portion, wherein the conductive structures comprising a formation of at least two rows.

2. (Original) The structure according to claim 1, further comprising:

an electrostatic discharge (ESD) protection device electrically connected to the first conductive layer.

3. (Original) The structure according to claim 1, wherein a material of the dielectric layer is a low dielectric constant material.

4. (Original) The structure according to claim 1, wherein the first conductive layer is a metal layer.

5. (Original) The structure according to claim 1, wherein the second conductive layer is a metal layer.

6-7. (Cancelled)

8. (Currently amended) A bonding pad structure, comprising:
a substrate having an interlevel dielectric (ILD) layer thereon,
a bonding pad formed on the ILD layer and substantially surrounded and insulated by an intermetal dielectric (IMD) layer, wherein the bonding pad comprises at least one metal layer having a wiring layer with a stripe layout and a first edge portion, a bonding metal layer having a wire bonding portion and a second edge portion and a plurality of plugs electrically connecting the wiring layer and the wire bonding portion; and

[[a]] an array of conductive structures surrounding the wire bonding portion, connecting the first edge portion and the second edge portion, wherein the conductive structures comprising a formation of at least two rows.

9. (Original) The structure according to claim 8, further comprising:
an electrostatic discharge (ESD) protection device electrically connected to the first conductive layer.

10. (Original) The structure according to claim 8, wherein a material of the IMD layer is a low dielectric constant material.

11-23. (Cancelled).

24. (Currently amended) A bonding pad structure, comprising:

a bonding pad substantially surrounded and insulated by a dielectric layer, wherein the bonding pad comprises at least one first conductive layer having a wiring layer with a stripe layout and a first edge portion, a second conductive layer having a wire bonding portion and a second edge portion and a plurality of first plugs electrically connecting the wiring layer and the wire bonding portion; and

an array of ~~metal~~ second plugs connecting the first edge portion and the second edge portion, wherein each of the second plugs has a dimension smaller than one of each of the first plugs.

25. (Previously presented) The structure according to claim 24, further comprising:

an electrostatic discharge (ESD) protection device electrically connected to the first conductive layer.

26. (Previously presented) The structure according to claim 24, wherein a material of the dielectric layer is a low dielectric constant material.

27. (Previously presented) The structure according to claim 24, wherein the first conductive layer is a metal layer.

28. (Previously presented) The structure according to claim 24, wherein the first conductive layer is a metal layer.